

UV-Ozone cleaning system

UV Clean is a cleaning system based on the the combined effects of UV-C radiation and Ozone. It can be used to clean and prepare parts for wire bonding, die attach or other special assembly operation. UV-Ozone cleaning is simple, not requiring gases or vacuum, and allows to obtain cleaning results similar to what can be obtained by other cleaning methods such as Plasma.

This cleaning system, combined with DI water pre cleaning and rinse, can be used in custom projects to design in-line cleaning machines, which will be a good alternative to plasma in case of mass productions. On silicon wafers, UV-Ozone can be used for epitaxy processes to increase oxide thickness, or to remove resist residues.

Specifications	
Operation	Semi automatic with motorized drawer platform (manual for Lab. unit)
Control	Microprocessor controlled with operator interface (only Auto version)
Lamps	180-250 nm UV Ozone generating lamps with electronic ballasts
Lifetime	minimum 7000 hours to reach a 50% lamp efficiency
Cleaning time	From a minimum of 90 seconds up (depending on surface contamination)
Typical applications	Wire bonding, die attach, Oxide increasing in silicon epitaxy processes
Platform Dimensions	350 mm W x 350 mm (60 mm x 350 Lab. unit)
Footprint	650 mm W x 600mm D x 220 mm H (80 x 400 x 110 Lab. unit)
Available versions	UVClean Auto - UvClean Lab unit (for laborator evaluation)
Facilities	AC 220 - 240 V - 2 A 50 /60 Hz Exhaust ø 100mm - 250 m3 h UVClean Auto Exhaust ø 32 mm UVClean Lab. Unit

(Specifications are subject to change without any obligation on the part of manufacturer)

